



(51) International Patent Classification:

H10N 69/00 (2023.01) *H01L 23/00* (2006.01)
G06N 10/40 (2022.01)

(21) International Application Number:

PCT/FI2024/050173

(22) International Filing Date:

16 April 2024 (16.04.2024)

(25) Filing Language:

English

(26) Publication Language:

English

(30) Priority Data:

20235525 10 May 2023 (10.05.2023) FI

(71) Applicant: IQM FINLAND OY [FI/FI]; Keilaranta 19,
02150 Espoo (FI).

(72) Inventors: PALMA, Mario; c/o IQM Finland Oy, Keila-
ranta 19, 02150 Espoo (FI). JENEI, Máté; c/o IQM Finland
Oy, Keilaranta 19, 02150 Espoo (FI). ORGIAZZI, Jean-
Luc; c/o IQM Finland Oy, Keilaranta 19, 02150 Espoo (FI).
AHMAD, Hasnain; c/o IQM Finland Oy, Keilaranta 19,
02150 Espoo (FI). TAN, Kuan; c/o IQM Finland Oy, Keila-
ranta 19, 02150 Espoo (FI).

(74) Agent: BERGGREN OY; P.O. Box 16, (Eteläinen
Rautatiekatu 10 A), 00101 Helsinki (FI).

(81) Designated States (unless otherwise indicated, for every
kind of national protection available): AE, AG, AL, AM,
AO, AT, AU, AZ, BA, BB, BG, BH, BN, BR, BW, BY, BZ,
CA, CH, CL, CN, CO, CR, CU, CV, CZ, DE, DJ, DK, DM,
DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT,
HN, HR, HU, ID, IL, IN, IQ, IR, IS, IT, JM, JO, JP, KE, KG,
KH, KN, KP, KR, KW, KZ, LA, LC, LK, LR, LS, LU, LY,
MA, MD, MG, MK, MN, MU, MW, MX, MY, MZ, NA,
NG, NI, NO, NZ, OM, PA, PE, PG, PH, PL, PT, QA, RO,
RS, RU, RW, SA, SC, SD, SE, SG, SK, SL, ST, SV, SY, TH,
TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, WS,
ZA, ZM, ZW.

(84) Designated States (unless otherwise indicated, for every
kind of regional protection available): ARIPO (BW, CV,
GH, GM, KE, LR, LS, MW, MZ, NA, RW, SC, SD, SL, ST,
SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ,
RU, TJ, TM), European (AL, AT, BE, BG, CH, CY, CZ,
DE, DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT,
LU, LV, MC, ME, MK, MT, NL, NO, PL, PT, RO, RS, SE,
SI, SK, SM, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN,
GQ, GW, KM, ML, MR, NE, SN, TD, TG).

(54) Title: SUPERCONDUCTING HARD-STOP FOR FLIP CHIP

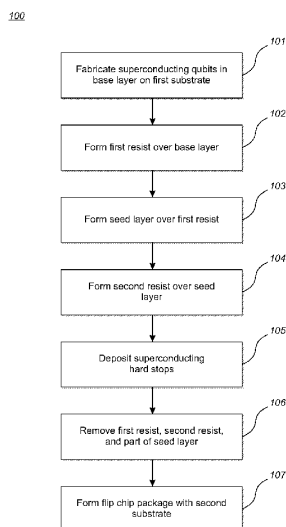


FIG. 1

(57) Abstract: The invention relates to the field of integrated circuit device fabrication, in particular to the fabrication of superconducting hard stops for flip chip devices. Superconducting hard stops are formed on a first substrate and are used to constrain the position of a second substrate relative to the first substrate.

Declarations under Rule 4.17:

- *as to applicant's entitlement to apply for and be granted a patent (Rule 4.17(ii))*
- *of inventorship (Rule 4.17(iv))*

Published:

- *with international search report (Art. 21(3))*